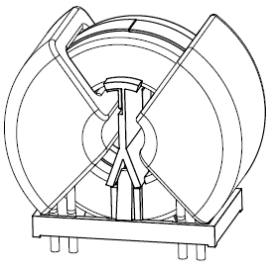


Chokes for Power Lines

Material Data Sheet

Product Class:	Ring Core Multi Choke B827xxE*****	
Date	23.09.2014	
IMDS ID if available		
Version:	02	

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt-%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	4B	Manganese-zinc ferrite	100	12645-49-7	60.0	
	Metal	1C	Cu	100	7440-50-8	30.4	
	Thermoplastic	2A	Polyester-imide (THEIC)	50	839-90-7	1.1	
			Polyamide-imide (PAI)	50	31957-38-7		
Encapsulation and Mounting	Thermoplastic	2A	Polycarbonate (PC)	90	25766-59-0	2.5	
			Fiberglass	10	65997-17-3		
	Polymer	2A	Polyamide 66 (PA)	67	32131-17-2	5.8	
			Red Phosphorous	8	7723-14-0		
			Fiberglass	25	65997-17-3		
Termination	Metal	1C	Sn	100	7440-31-5	0.1	
Label	Polymer	2C	Polyethylenterephthalate PET	100	25038-59-9	0.1	
	Polymer	2C	Acrylic resin	100	37325-11-4		X
Sum in total:						100.0	

Size W x L x H [max. in mm]	Weight [approx. in g]	Part Numbers	Size W x L x H [max. in mm]	Weight [approx. in g]	Part Numbers
65x35x66	200	B82727E6503A040	48x56x49	85	B82726E6263A040
	220	B82727E6443A040		90	B82726E6243A041
	245	B82727E6403A040		100	B82726E6213A040
	200	B82727E6243A040			
	210	B82727E6223A040			
56x34x57	120	B82726E6333B040	65x37x71	220	B82747E6353A040
	140	B82726E6283B040		210	B82747E6253A040
	155	B82726E6203B041		205	B82747E6203A040
	165	B82726E6123B030		200	B82747E6163A040
	145	B82726E6223B030			

Contact	Dr. Johann Reindl, MAG EPQM	Important remarks: 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated. 2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.
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*) others: not declarable or prohibited substances acc. GADSL
 **) typical mass percentage of substance

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (valid not valid)

- no exemptions;**
- Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
- Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;
- Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
- Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
- Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
- Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
- Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
- Other Exemption than above